

Semiconductor Die with Solderable Metal System Allowing Direct Surface Mounting to Printed Circuit Boards

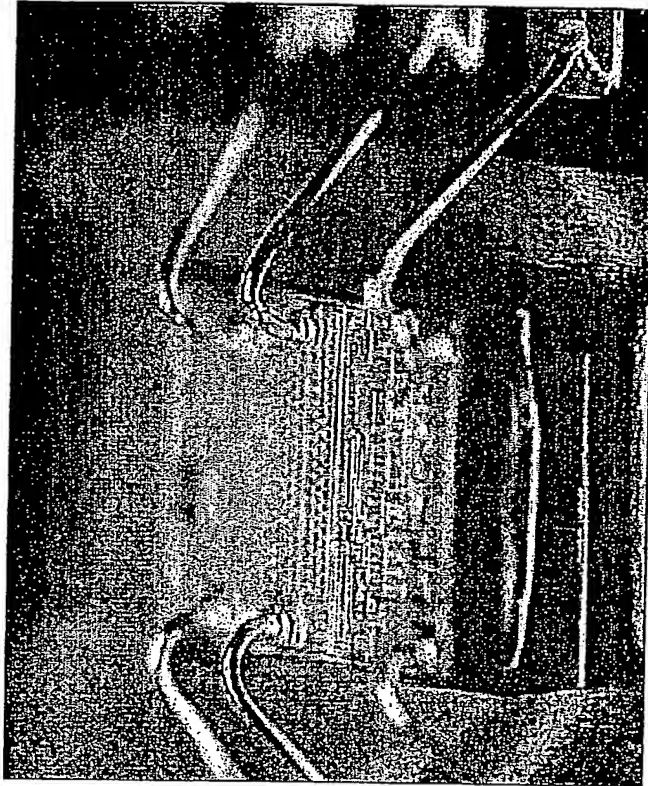


Figure 1. Example of Wire Bonding Used to Form the Electrical Connections to the Semiconductor Die

Semiconductor Die with Solderable Metal System Allowing Direct Surface Mounting to Printed Circuit Boards

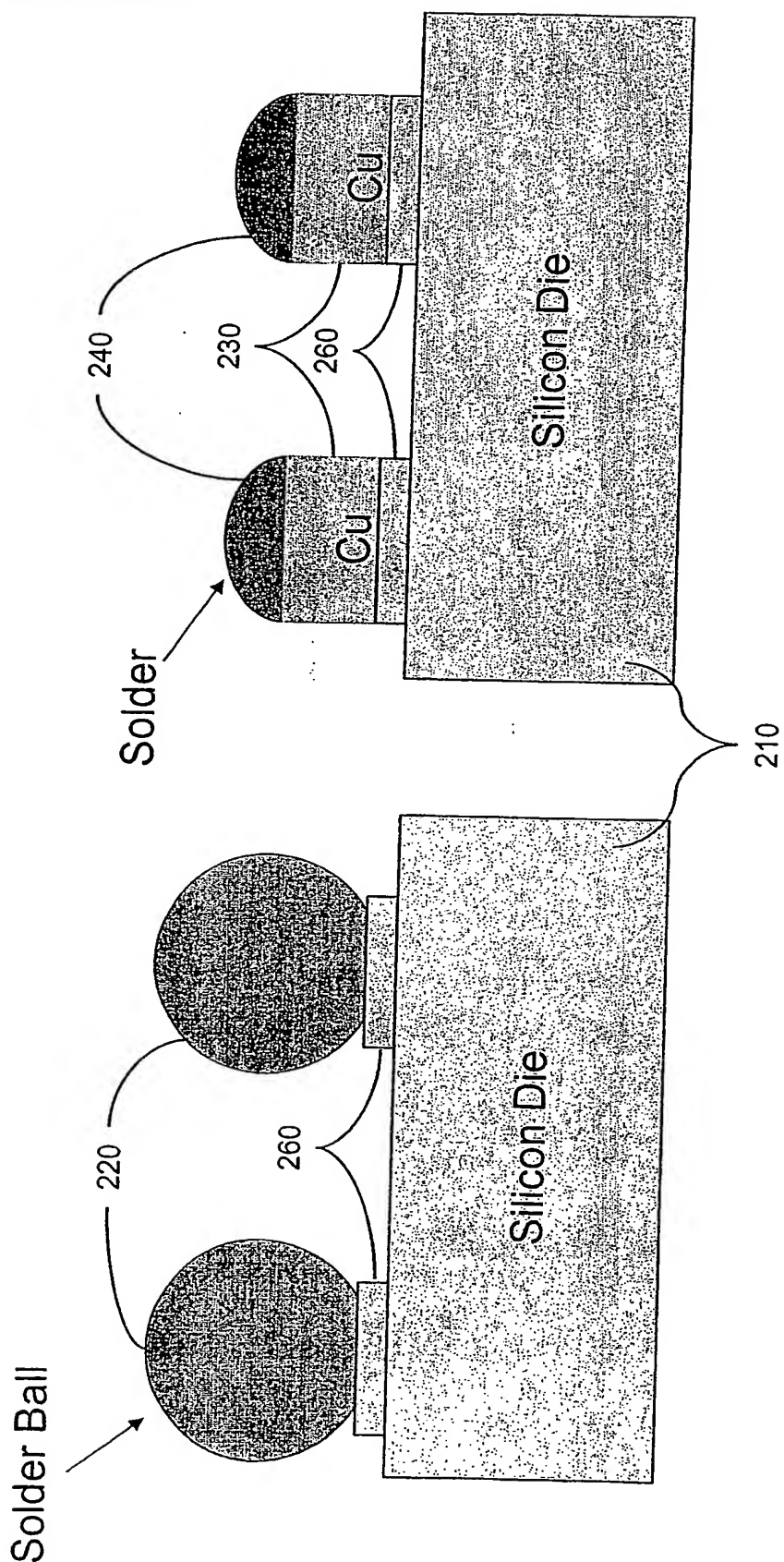
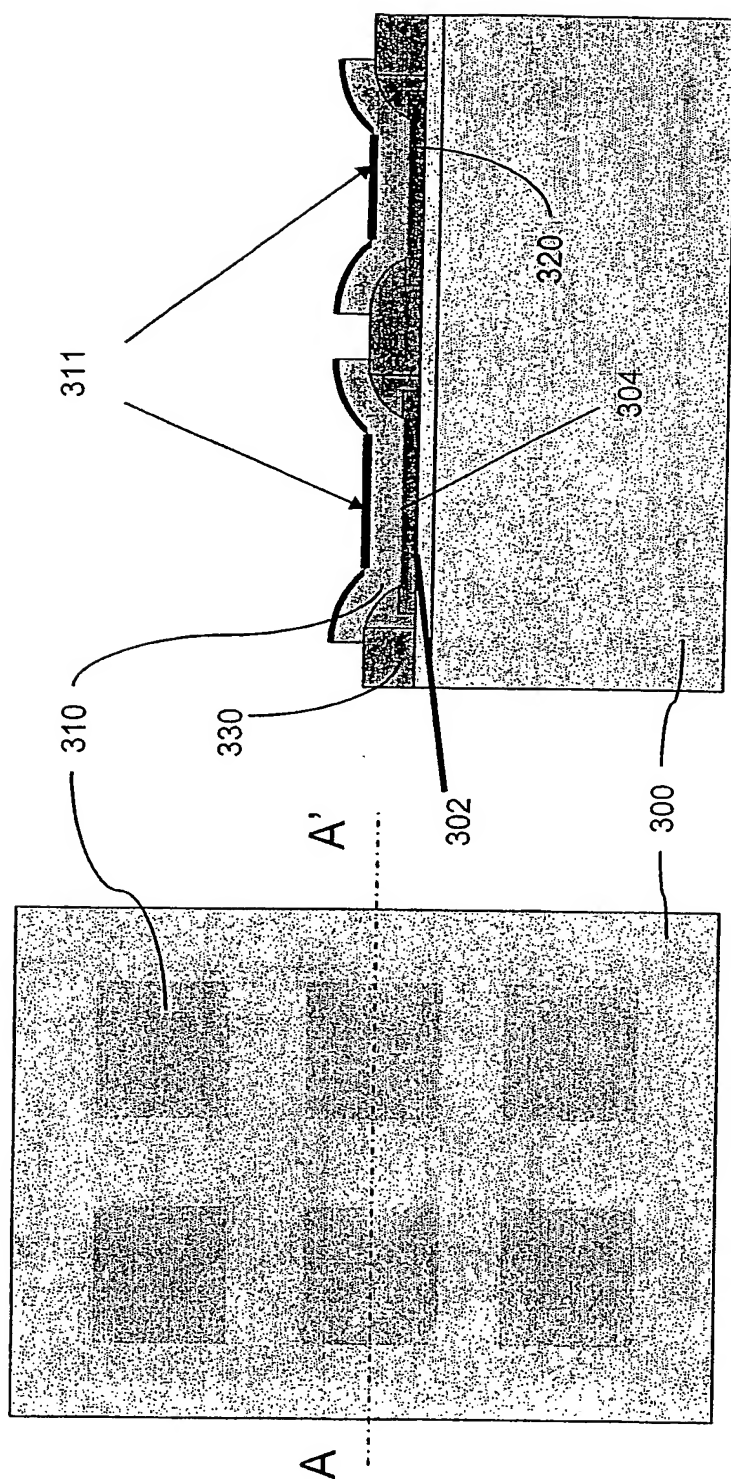


Figure 2. Typical Flip Chip Wafer Bumping Packages

Semiconductor Die with Solderable Metal System Allowing Direct Surface Mounting to Printed Circuit Boards



Top View

Cross-Sectional View (A-A')

Figure 3. Die with Solderable Metal Contacts for Direct Printed Circuit Board Mounting

Semiconductor Die with Solderable Metal System Allowing Direct Surface Mounting to Printed Circuit Boards

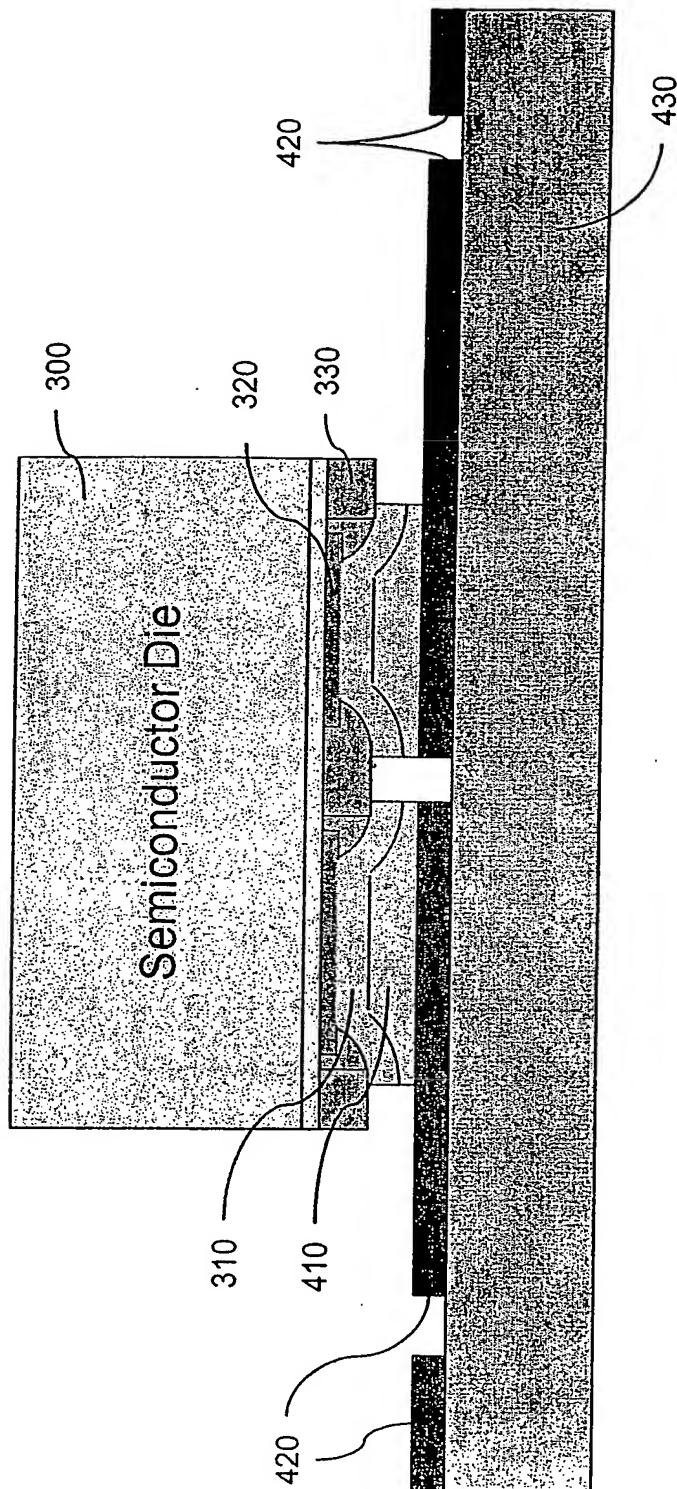


Figure 4. Illustration of Die with Solderable Electrical Contacts Mounted on Printed Circuit Board